Title (en)

LEADLESS FREE-CUTTING COPPER ALLOY

Title (de)

BLEIFREIE AUTOMATENKUPFERLEGIERUNG

Title (fr)

ALLIAGE DE CUIVRE DE DECOLLETAGE SANS PLOMB

Publication

EP 1045041 A4 20030507 (EN)

Application

EP 98953071 A 19981116

Priority

- JP 9805157 W 19981116
- JP 28859098 A 19981012

Abstract (en)

[origin: EP1559802A1] Lead-free copper alloys with industrially satisfactory machinability comprising 69 to 79 percent, by weight, of copper, 2.0 to 4.0 percent, by weight, of silicon, and the remaining percent, by weight, of zinc. <IMAGE>

IPC 1-7

C22C 9/04; C22F 1/08

IPC 8 full level

C22F 1/00 (2006.01); **C22C 9/04** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP KR)

C22C 9/04 (2013.01 - EP KR); **C22F 1/08** (2013.01 - EP)

Citation (search report)

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